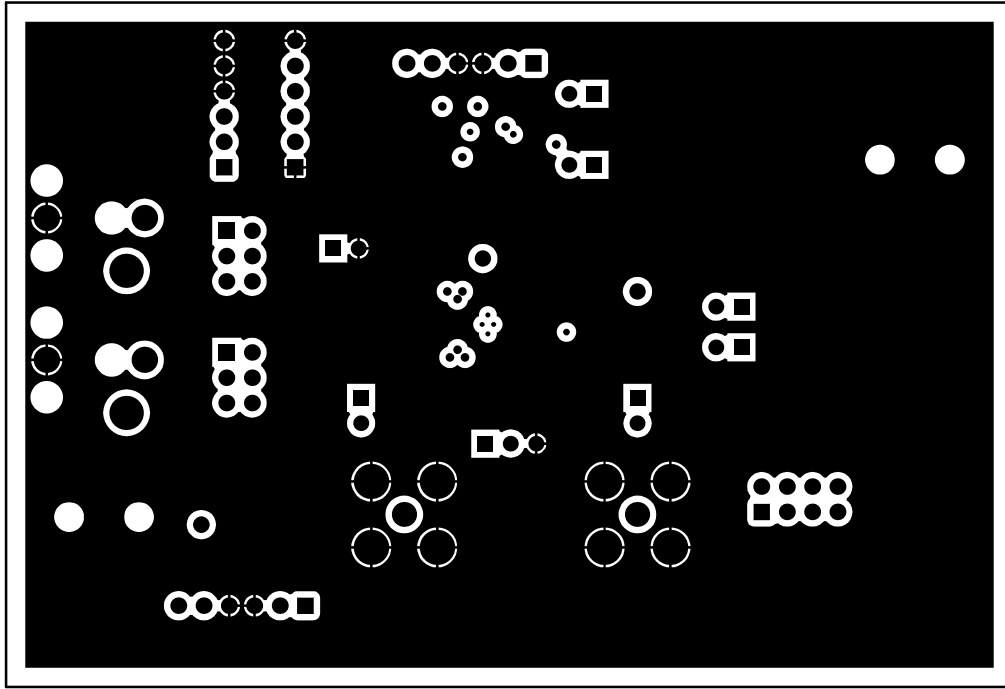
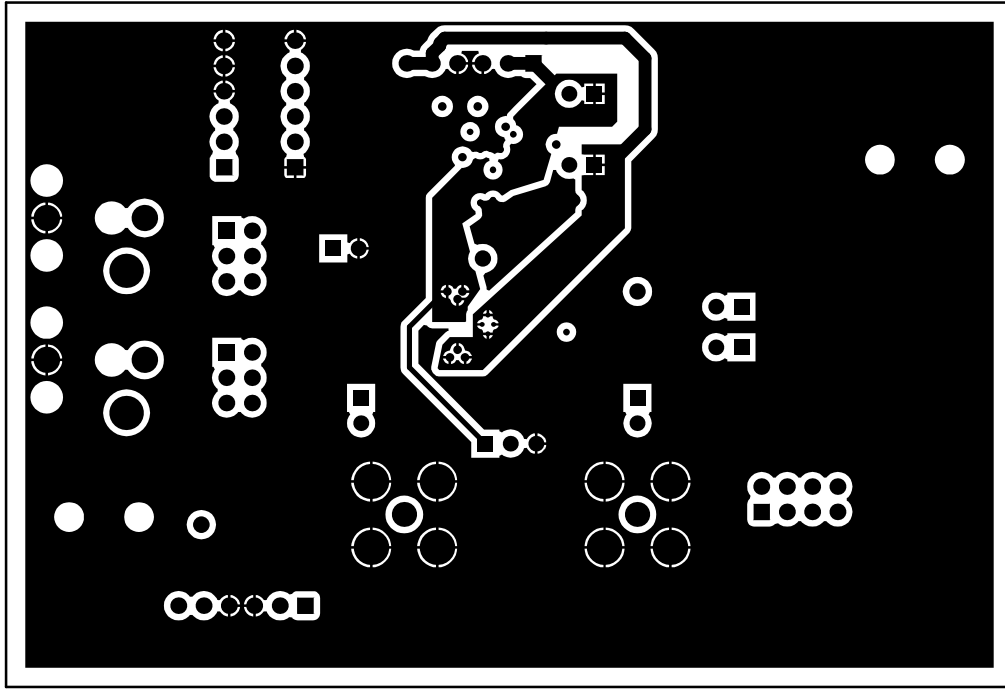


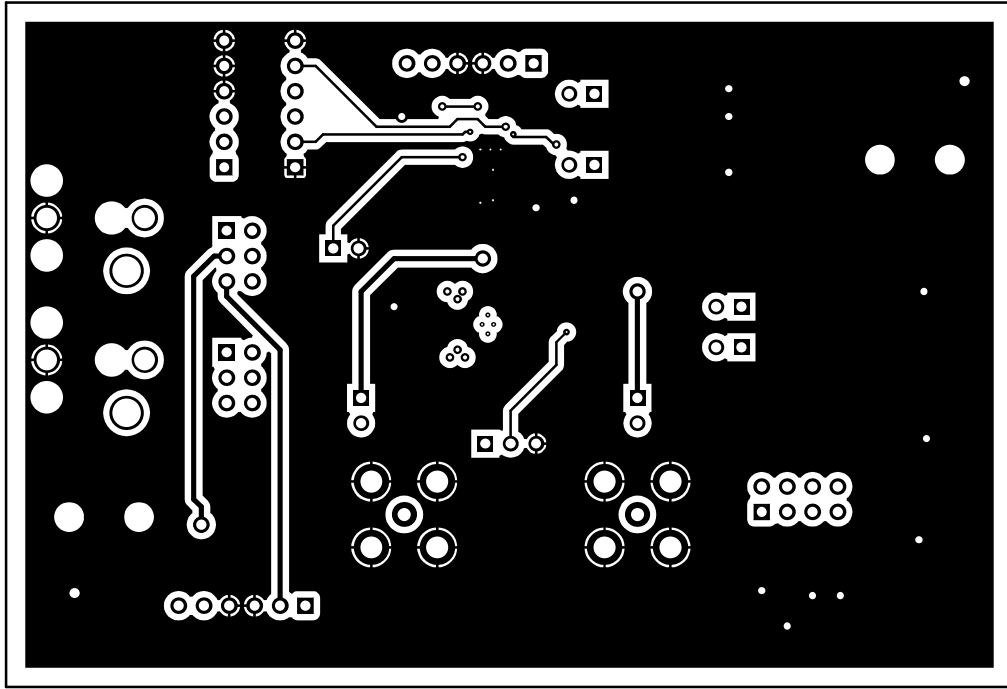
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01341	REV: A1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01341		
PLOT NAME = Top Layer	GENERATED : 3.1.2017	13:11:05	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01341	REV: A1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01341		
PLOT NAME = Signal 1	GENERATED : 3.1.2017 13:11:06	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01341	REV: A1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01341		
PLOT NAME = Signal 2	GENERATED : 3.1.2017 13:11:07	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01341	REV: A1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01341		
PLOT NAME = Bottom Layer	GENERATED : 3.1.2017	13:11:08	TEXAS INSTRUMENTS

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